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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :

Hiroaki INOUE et al :

Serial No. 09/980,455 : 09/890,455

Filed: March 12, 2002 :

Attention of Initial Patent
Examination Customer Service
Center

Title: Electroless plating solution
and method for forming wiring with the same

REQUEST FOR CORRECTED FILING RECEIPT

RECEIVED

Assistant Commissioner for Patents,
Washington, D. C.

APR 22 2003

GROUP 3600

Sir:

Enclosed herewith is a copy of the Official Filing
Receipt for the above-identified application marked in
red indicating corrections to be made thereto.

Accordingly, it is requested that the PTO issue a
Corrected Filing Receipt reflecting these corrections.

Respectfully submitted,

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March 17, 2003



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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/890,455	03/12/2002	1755	1150	2001-1091A	3	12	4

CONFIRMATION NO. 3064

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FILING RECEIPT



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Date Mailed: 04/02/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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Foreign Applications

JAPAN 11-365464 12/22/1999

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Title

Electroless plating solution and method of forming wiring with the same